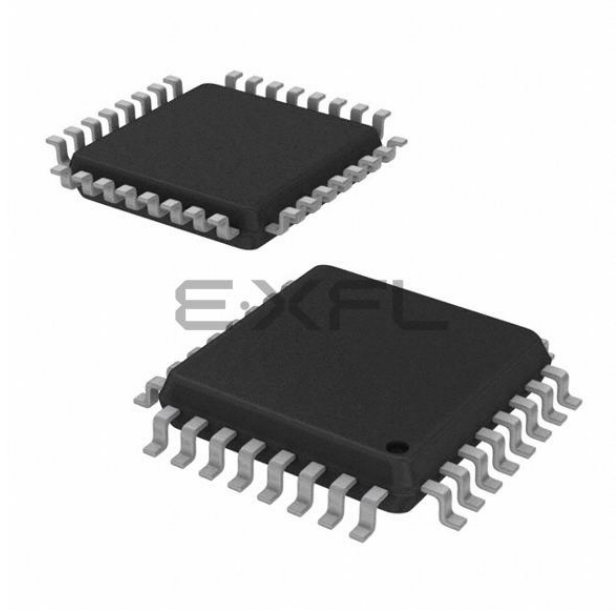

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What is "Embedded - Microcontrollers"?

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	STM8A
Core Size	8-Bit
Speed	24MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm8af6286tax

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Table 55. Document revision history (continued)

Date	Revision	Changes
18-Jul-2012	9 (continued)	*Table 26: Total current consumption in Run, Wait and Slow mode. General conditions for VDD apply, TA = -40 °C to 150 °C:* updated conditions for $I_{DD(RUN)}$. *Table 38: I/O static characteristics:* added new condition and new max values for rise and fall time; updated footnote *2*. *Section 10.3.7: Reset pin characteristics:* updated text below *Figure 38: Typical NRST pull-up current Ipu vs VDD* *Figure 39: Recommended reset pin protection:* updated unit of capacitor. *Table 41: SPI characteristics:* updated SCK high and low time conditions and values. *Figure 42: SPI timing diagram - master mode:* replaced 'SCK input' signals with 'SCK output' signals. Updated *Table 49: LQFP80 - 80-pin, 14 x 14 mm low-profile quad flat package mechanical data*, *Table 50: LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package mechanical data*, *Table 51: LQFP48 - 48-pin, 7 x 7 mm low-profile quad flat package mechanical data*, *Table 52: LQFP32 - 32-pin, 7 x 7 mm low-profile quad flat package mechanical data*, *Table 53: VFQFPN32 - 32-pin, 5 x 5 mm, 0.5 mm pitch very thin profile fine pitch quad flat package mechanical data* Replaced *Figure 48: LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package outline*, *Figure 51: LQFP48 - 48-pin, 7 x 7 mm low-profile quad flat package outline* and *Figure 54: LQFP32 - 32-pin, 7 x 7 mm low-profile quad flat package outline* Added *Figure 49: LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package recommended footprint*, *Figure 52: LQFP48 - 48-pin, 7 x 7 mm low-profile quad flat package recommended footprint* and *Figure 55: LQFP32 - 32-pin, 7 x 7 mm low-profile quad flat package recommended footprint* Updated *Figure 57: VFQFPN32 - 32-pin, 5x5 mm, 0.5 mm pitch very thin profile fine pitch quad flat package outline* Updated *Figure 60: STM8AF526x/8x/Ax and STM8AF6269/8x/Ax ordering information scheme1* *Section 13.2.2: C and assembly toolchains:* added www.iar.com.
31-Mar-2014	10	Updated: – *Table 1: Device summary*, – *Table: STM8AF52xx product line-up with CAN*, – *Table: STM8AF/H/P51xx product line-up with CAN*, – *Table: STM8AF/H/P61xx product line-up without CAN*, – *Table 11: STM8AF526x/8x/Ax and STM8AF6269/8x/Ax pin description*, – The maximum speed in *Section 5.9.3: Serial peripheral interface (SPI)*, – t_{TEMP} Reset release delay /VDD rising typical and max values in *Table 25: Operating conditions at power-up/power-down*, – The symbol $t_{IFP(NRST)}$ with $t_{INFP(NRST)}$ in *Table 39: NRST pin characteristics*, – The address and comment for Reset in *Table 17: STM8A interrupt table*.

Table 55. Document revision history (continued)

Date	Revision	Changes
31-Mar-2014	10 (continued)	Added: – *Figure 7: STM8AF52x6 VFQFPN32 32-pin pinout;* – the caution in *Section 5.10: Input/output specifications,* – The table footnote “Not recommended for new designs” to *Table: STM8AF/H/P51xx product line-up with CAN* and *Table: STM8AF/H/P61xx product line-up without CAN.* – The figure footnotes to *Figure 7: STM8AF52x6 VFQFPN32 32-pin pinout* and *Figure: VFQFPN 32-lead very thin fine pitch quad flat no-lead package (5 x 5)*
13-Jun-2014	11	Added STM8AF52A6 part number.
09-Jun-2015	12	Added: – the third table footnote to *Table 25: Operating conditions at power-up/power-down*, – *Figure 47: LQFP80 marking example (package top view)*, – *Figure 50: LQFP64 marking example (package top view)*, – *Figure 53: LQFP48 marking example (package top view)*, – *Figure 56: LQFP32 marking example (package top view)*, – *Figure 59: VFQFPN32 marking example (package top view)*, – the footnote about the device marking to *Figure 60: STM8AF526x/8x/Ax and STM8AF6269/8x/Ax ordering information scheme1*. Removed STM8AF51xx and STM8AF61xx obsolete root part numbers, and consequently “H” products: – *Table 1: Device summary*, – *Section 1: Introduction*, – *Section 2: Description*, – *Section 3: Product line-up*, – *Table 12: Memory model 128K*, – *Section 10.3: Operating conditions*, – *Figure 60: STM8AF526x/8x/Ax and STM8AF6269/8x/Ax ordering information scheme1*. Moved *Section 11.6: Thermal characteristics* to *Section 11: Package information*. Updated: – the product naming in the document headers and captions, – the standard reference for EMI characteristics in *Table 46: EMI data*.
13-Jun-2016	13	Updated *Table 53: VFQFPN32 - 32-pin, 5 x 5 mm, 0.5 mm pitch very thin profile fine pitch quad flat package mechanical data*

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